

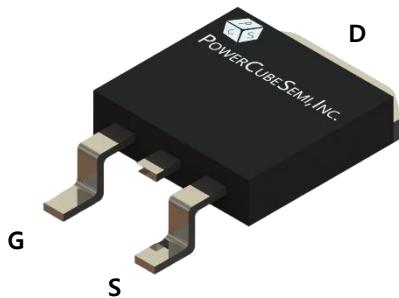
# PSZ22065D

650V 22A 190mΩ Si Super junction MOSFET with Zener Diode

## Features

### Si Super junction MOSFET

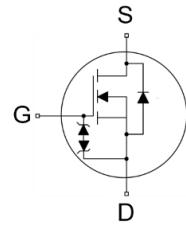
- Rated to 650V at 22Amps @ $T_j = 25^\circ\text{C}$
- Max  $R_{DS(on)} = 190 \text{ m}\Omega$
- Typ  $R_{DS(on)} = 150 \text{ m}\Omega$
- Gate Charge(Typ.  $Q_g=40 \text{ nC}$ )
- Excellent ESD robustness <6kV (HBM)
- Improved dv/dt Capability
- 100% Avalanche Tested



PKG type : D2PAK (TO-263)

## Application

- LCD/LED/PDP TV
- Telecom/Server Power supplies
- AC-DC Power Supply
- LED Lighting



## Description

PSZ22065D is PowerCubeSemi's second generation of high voltage Super Junction MOSFET that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, the combination of Super Junction MOSFET is suitable for various AC/DC power conversion for system miniaturization and higher efficiency

## Absolute Maximum Ratings

Symbol	Parameter	Test Condition	Value	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=1\text{mA}$	650	V
$I_D$	Drain Current	$T_c=25^\circ\text{C}$	22	A
$I_{DM}$	Pulsed Drain Current	Pulse width limited by junction temperature	50	A
$V_{GS}$	Gate-Source Voltage		$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy	$I_{AS}=9\text{A}, R_G=25\Omega, V_{DD}=50\text{V}$	113	mJ
$P_d$	Power Dissipation	$T_c=25^\circ\text{C}$	TBD	W
$T_j$	Operating Junction Temperature		150	°C
$T_{stg}$	Storage Temperature		-55 to 150	°C



## Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Tape width	Quantity
PSZ22065D	PSZ22065	TO-263	REEL	-	-

## Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ.	Max.	
$BV_{DSS}$	Drain-source breakdown voltage	$V_{GS} = 0V, I_D = 1mA, T_J = 25^\circ C$	650	-	-	V
$I_{DSS}$	Zero gate voltage drain current	$V_{DS} = 650V, V_{GS} = 0V$	-	-	10	$\mu A$
$I_{GSS}$	Gate-source leakage current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	$\pm 3$	$\mu A$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 1mA$	3	-	5	V
$R_{DS(ON)}$	Static drain-source on state resistance	$V_{GS} = 10V, I_D = 10A$	-	150	190	$m\Omega$
$t_{d(on)}$	Turn-on Delay time	$V_{DD} = 380 V, I_D = 10A, V_{GS} = 10 V, R_G = 4.7\Omega$	-	20	-	ns
$T_r$	Turn-on Rise time		-	8	-	
$t_{d(off)}$	Turn-off Delay time		-	64	-	
$T_f$	Turn-off Fall time		-	14	-	



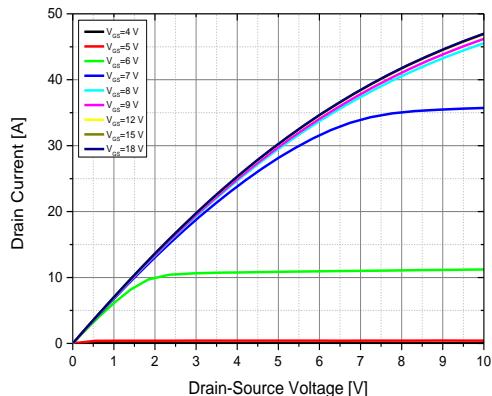
## Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
$R_{\theta JC}$	Thermal resistance, Junction to case		TBD	-	°C/W
$R_g$	Gate resistance	$V_{GS} = 0V, f = 1MHz$	4	5	Ω
$C_{iss}$	Input capacitance	$V_{DS} = 380V, V_{GS} = 0V, f = 200kHz$	1750	-	pF
$C_{oss}$	Output capacitance		39	-	
$C_{rss}$	Reverse transfer capacitance		2	-	
$Q_{g(tot)}$	Total gate charge at 10V	$V_{DS} = 380V, I_D = 10A$ $V_{GS(on)} = 10V, V_{GS(off)} = 0V$	40	-	nC
$Q_{gs}$	Gate to source gate charge		8	-	
$Q_{gd}$	Gate to drain "Miller" charge		15	-	

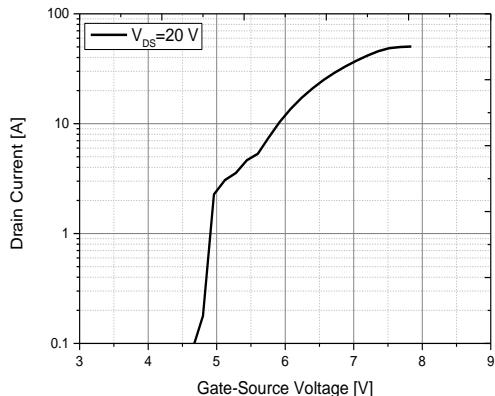
## Electrical Characteristics of Si Diode

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
$I_S$	Maximum continuous drain to source diode forward current		-	20	A
$I_{SM}$	Maximum pulsed drain to source diode forward current		-	50	A
$V_{SD}$	Drain to source diode forward voltage	$I_{SD} = 10A, V_{GS} = 0V$	0.9	-	V
$T_{rr}$	Reverse recovery time	$I_{SD} = 10A, V_{DD} = 400V, dI_F/dt=100A/\mu s$	310	-	ns
$Q_{rr}$	Reverse recovery charge		3.9	-	μC
$I_{rrm}$	Reverse recovery current		25	-	A

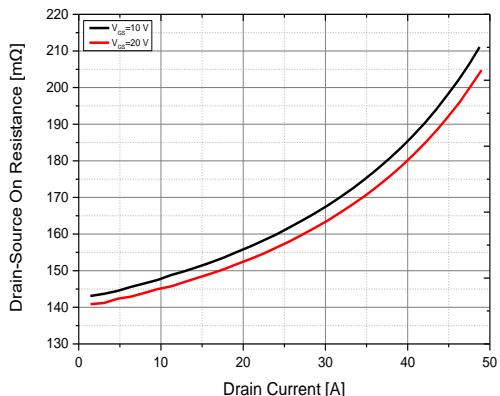
# Typical Characteristics



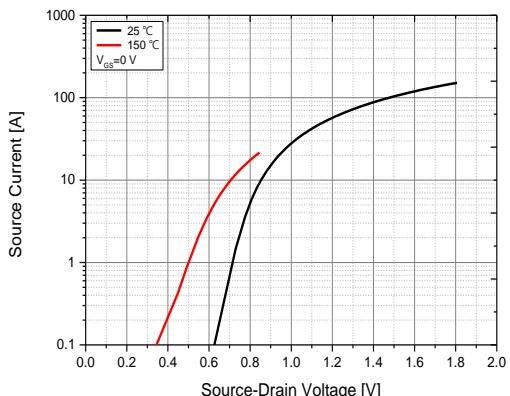
**Figure 1. On-state characteristics**



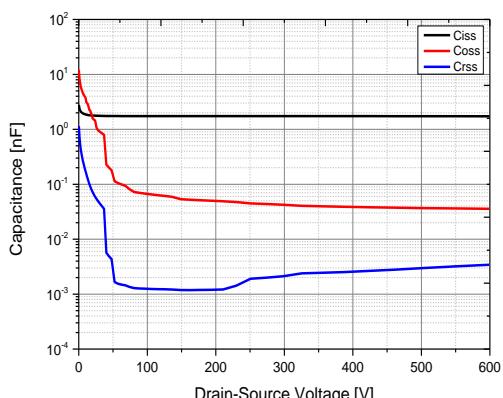
**Figure 2. Transfer Characteristics**



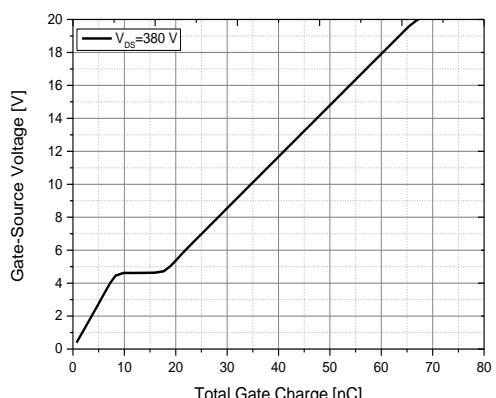
**Figure 3. On Resistance Variation vs Drain Current and Gate Voltage**



**Figure 4. Body Forward Voltage Variation vs Source Current and Temperature**

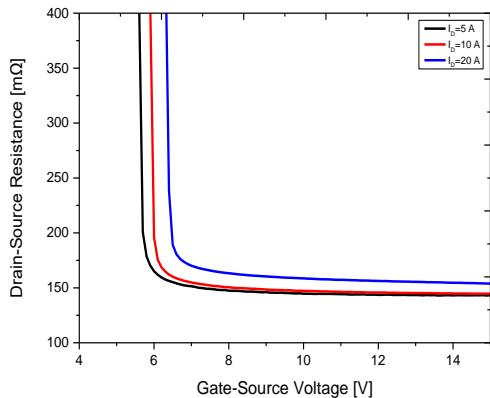


**Figure 5. Capacitance Characteristics**

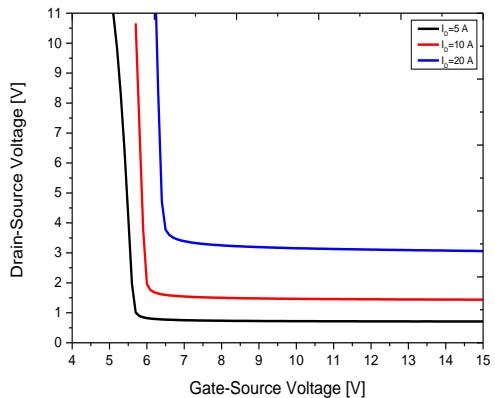


**Figure 6. Gate Charge Characteristics**

# Typical Characteristics



**Figure 7. Drain to Source Resistance vs Gate to Source Voltage**

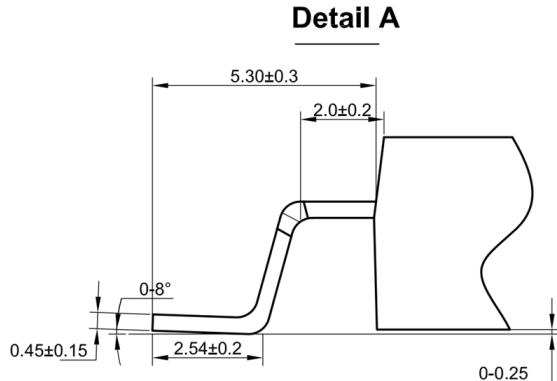
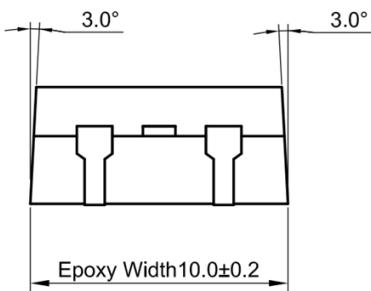
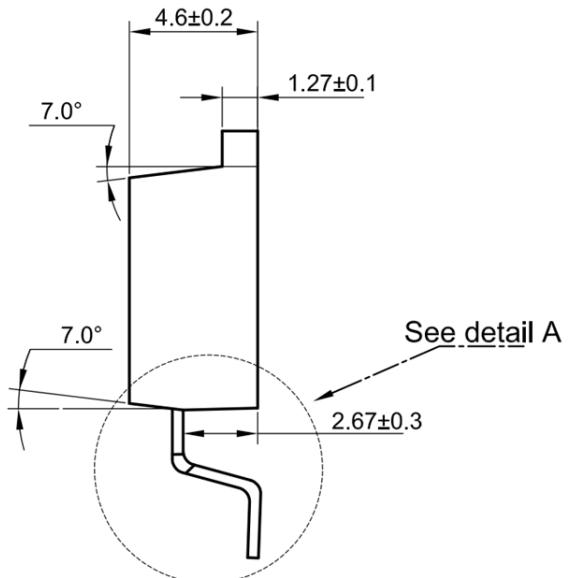
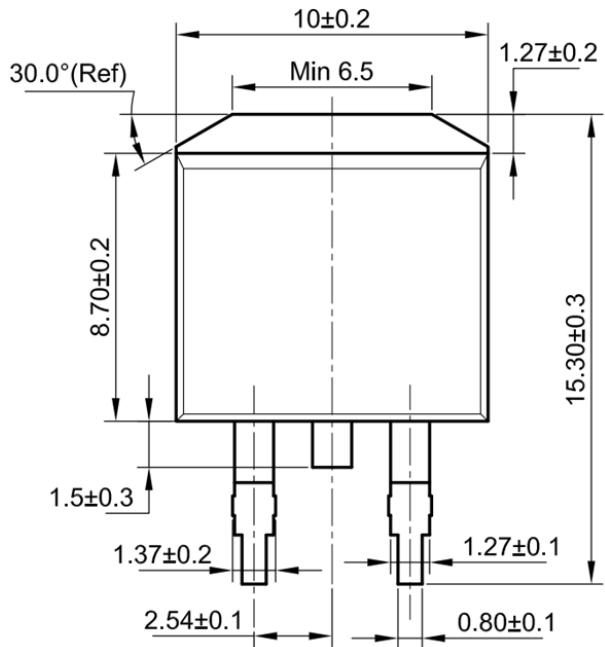


**Figure 8. Drain to Source Voltage vs Gate to Source Voltage**



## Package Outline

[Unit : mm]



## Revision History

Version	Data of release	Description of changes
Rev. 1.0	2024-05-10	Final Datasheet